

Appl. No. : Unkown
Filed : Herewith

AMENDMENTS TO THE CLAIMS

1. **(Original)** A resin for a photoresist composition, having a hydroxyl group bonded to a carbon atom at a polymer terminal, wherein a carbon atom in an α -position to said hydroxyl group has at least one electron attractive group.
2. **(Original)** A resin for a photoresist composition according to claim 1, having a $-\text{CR}^1\text{R}^2\text{OH}$ group at a polymer terminal, wherein R^1 and R^2 each represent, independently, an alkyl group, halogen atom, or halogenated alkyl group, and at least one of R^1 and R^2 is an electron attractive group selected from a group consisting of halogen atoms and halogenated alkyl groups.
3. **(Original)** A resin for a photoresist composition according to claim 1, wherein said electron attractive group is a fluorine atom or a fluorinated alkyl group.
4. **(Original)** A resin for a photoresist composition according to claim 2, wherein a proportion of structural units (M1) comprising said $-\text{CR}^1\text{R}^2\text{OH}$ group is at least 1 mol%, relative to a combined 100 mol% of all structural units other than said structural units (M1) within said resin for a photoresist composition.
5. **(Original)** A resin for a photoresist composition, having a substituent with a pKa value within a range from 6 to 12 at a polymer terminal.

Appl. No. : Unkown
Filed : Herewith

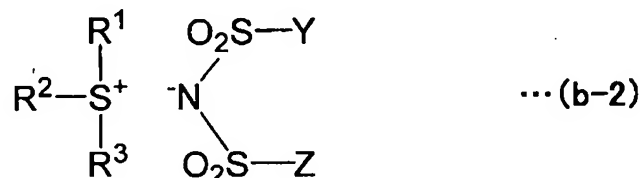
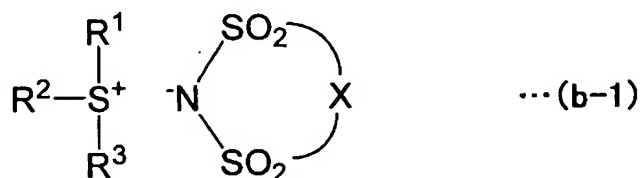
6. **(Original)** A resin for a photoresist composition according to claim 5, wherein said substituent is a $-CR^1R^2OH$ group, wherein R^1 and R^2 each represent, independently, an alkyl group, halogen atom, or halogenated alkyl group, and at least one of R^1 and R^2 is an electron attractive group selected from a group consisting of halogen atoms and halogenated alkyl groups.
7. **(Currently amended)** A resin for a photoresist composition according to claim 1 ~~or~~ 5, further comprising an acid dissociable, dissolution inhibiting group.
8. **(Original)** A resin for a photoresist composition according to claim 7, further comprising (a1) a structural unit derived from a (meth)acrylate ester having an acid dissociable, dissolution inhibiting group, and (a2) a structural unit derived from a (meth)acrylate ester having a lactone ring.
9. **(Original)** A resin for a photoresist composition according to claim 8, further comprising (a3) a structural unit derived from a (meth)acrylate ester having a hydroxyl group.
10. **(Currently amended)** A resin for a photoresist composition according to claim 1 ~~or~~ 9, with a weight average molecular weight of no more than 12,000.
11. **(Currently amended)** A photoresist composition, comprising a resin for a photoresist composition according to claim 1 ~~or~~ 5.

Appl. No. : Unkown
 Filed : Herewith

12. **(Original)** A photoresist composition according to claim 11, further comprising an acid generator as a component (B).

13. **(Original)** A photoresist composition according to claim 12, comprising as said component (B), (b-0) an onium salt that comprises a fluorinated alkylsulfonate ion as an anion.

14. **(Original)** A photoresist composition according to claim 12, comprising as said component (B), a sulfonium compound represented by either of general formulas (b-1) and (b-2) shown below:



wherein, X represents an alkylene group of 2 to 6 carbon atoms in which at least one hydrogen atom has been substituted with a fluorine atom; Y and Z each represent, independently, an alkyl group of 1 to 10 carbon atoms in which at least one hydrogen atom has been substituted with a fluorine atom; R^1 to R^3 each represent, independently, an aryl group or an alkyl group, and at least one of R^1 to R^3 is an aryl group.

Appl. No. : **Unkown**
Filed : **Herewith**

15. **(Original)** A photoresist composition according to claim 14, further comprising as said component (B), (b-0) an onium salt that comprises a fluorinated alkylsulfonate ion as an anion.

16. **(Original)** A photoresist composition according to claim 11, further comprising a nitrogen-containing organic compound.

17. **(Original)** A method for forming a resist pattern, using a photoresist composition according to claim 11.